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THIS SPEC IS OBSOLETE

Spec No: 38-05352

Spec Title: CY7C1444AV33, 36-MBIT (1M X 36) PIPELINED DCD SYNC SRAM

Replaced by: None

CY7C1444AV33

36-Mbit (1M × 36) Pipelined DCD Sync SRAM

Features

- Supports bus operation up to 250 MHz
- Available speed grades are 250 MHz and 167 MHz
- Registered inputs and outputs for pipelined operation
- Optimal for performance (double-cycle deselect)
- Depth expansion without wait state
- 3.3 V core power supply
- 2.5 V/3.3 V I/O power supply
- Fast clock-to-output times
  - 2.6 ns (for 250-MHz device)
- Provide high-performance 3-1-1-1 access rate
- User-selectable burst counter supporting Intel® Pentium® interleaved or linear burst sequences
- Separate processor and controller address strobes
- Synchronous self-timed writes
- Asynchronous output enable
- CY7C1444AV33 available in JEDEC-standard Pb-free 100-pin TQFP package
- "ZZ" sleep mode option

Functional Description

The CY7C1444AV33 SRAM integrates 1M × 36 SRAM cells with advanced synchronous peripheral circuitry and a two-bit counter for internal burst operation. All synchronous inputs are gated by registers controlled by a positive-edge-triggered clock input (CLK). The synchronous inputs include all addresses, all data inputs, address-pipelining chip enable ($\overline{CE_1}$), depth-expansion chip enables (CE_2 and $\overline{CE_3}$), burst control inputs (ADSC, ADSP, and ADV), write enables (BW_X, and $\overline{BWE}$), and global write ($\overline{GW}$). Asynchronous inputs include the output enable ($\overline{OE}$) and the ZZ pin.

Addresses and chip enables are registered at rising edge of clock when either address strobe processor (ADSP) or address strobe controller (ADSC) are active. Subsequent burst addresses can be internally generated as controlled by the advance pin (ADV).

Address, data inputs, and write controls are registered on-chip to initiate a self-timed write cycle. This part supports byte write operations (see Pin Descriptions and Truth Table for further details). Write cycles can be one to four bytes wide as controlled by the byte write control inputs. GW active LOW causes all bytes to be written. This device incorporates an additional pipelined enable register which delays turning off the output buffers an additional cycle when a deselect is executed. This feature allows depth expansion without penalizing system performance.

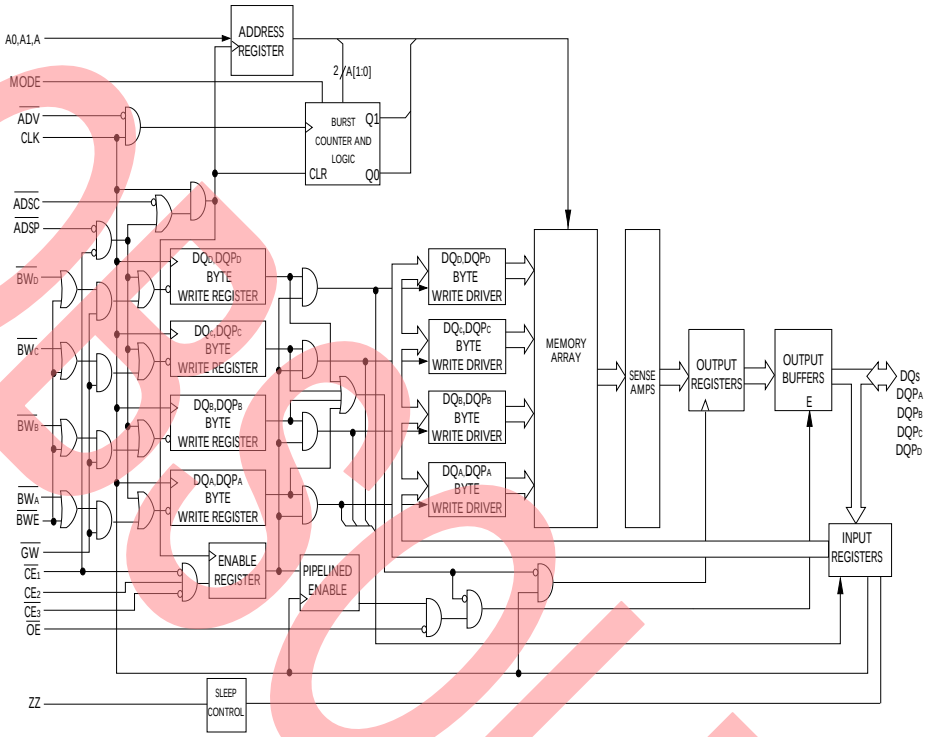
The CY7C1444AV33 operates from a +3.3 V core power supply while all outputs operate with a +3.3 V or a +2.5 V supply. All inputs and outputs are JEDEC-standard JESD8-5-compatible.

For a complete list of related documentation, click here.

Selection Guide

Description	250 MHz	167 MHz	Unit
Maximum access time	2.6	3.4	ns
Maximum operating current	475	375	mA
Maximum CMOS standby current	120	120	mA

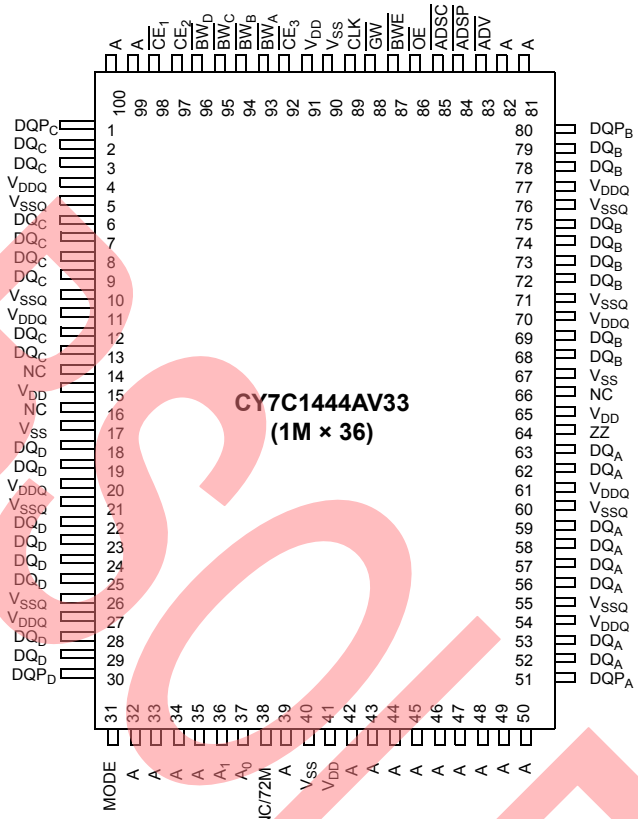
Logic Block Diagram – CY7C1444AV33



Contents

Pin Configurations

Figure 1. 100-pin TQFP (14 × 20 × 1.4 mm) pinout



Pin Definitions

Name	I/O	Description
A_0, A_1, A	Input-synchronous	**Address inputs used to select one of the address locations**. Sampled at the rising edge of the CLK if $\overline{ADSP}$ or $\overline{ADSC}$ is active LOW, and $\overline{CE}_1$, CE_2, and $\overline{CE}_3$ are sampled active. A1:A0 are fed to the two-bit counter.
$\overline{BW}_A$, $\overline{BW}_B$, $\overline{BW}_C$, $\overline{BW}_D$	Input-synchronous	**Byte write select inputs, active LOW**. Qualified with $\overline{BWE}$ to conduct byte writes to the SRAM. Sampled on the rising edge of CLK.
$\overline{GW}$	Input-synchronous	**Global write enable input, active LOW**. When asserted LOW on the rising edge of CLK, a global write is conducted (all bytes are written, regardless of the values on $\overline{BW}_X$ and $\overline{BWE}$).
$\overline{BWE}$	Input-synchronous	**Byte write enable input, active LOW**. Sampled on the rising edge of CLK. This signal must be asserted LOW to conduct a byte write.
CLK	Input-clock	**Clock input**. Used to capture all synchronous inputs to the device. Also used to increment the burst counter when $\overline{ADV}$ is asserted LOW, during a burst operation.
$\overline{CE}_1$	Input-synchronous	**Chip enable 1 input, active LOW**. Sampled on the rising edge of CLK. Used in conjunction with CE_2 and $\overline{CE}_3$ to select/deselect the device. $\overline{ADSP}$ is ignored if $\overline{CE}_1$ is HIGH. $\overline{CE}_1$ is sampled only when a new external address is loaded.
CE_2	Input-synchronous	**Chip enable 2 input, active HIGH**. Sampled on the rising edge of CLK. Used in conjunction with $\overline{CE}_1$ and $\overline{CE}_3$ to select/deselect the device. CE_2 is sampled only when a new external address is loaded.
$\overline{CE}_3$	Input-synchronous	**Chip enable 3 input, active LOW**. Sampled on the rising edge of CLK. Used in conjunction with $\overline{CE}_1$ and CE_2 to select/deselect the device. $\overline{CE}_3$ is sampled only when a new external address is loaded.
$\overline{OE}$	Input-asynchronous	**Output enable, asynchronous input, active LOW**. Controls the direction of the I/O pins. When LOW, the I/O pins behave as outputs. When deasserted HIGH, DQ pins are tri-stated, and act as input data pins. $\overline{OE}$ is masked during the first clock of a read cycle when emerging from a deselected state.
$\overline{ADV}$	Input-synchronous	**Advance input signal, sampled on the rising edge of CLK, active LOW**. When asserted, it automatically increments the address in a burst cycle.
$\overline{ADSP}$	Input-synchronous	**Address strobe from processor, sampled on the rising edge of CLK, active LOW**. When asserted LOW, addresses presented to the device are captured in the address registers. A1: A0 are also loaded into the burst counter. When $\overline{ADSP}$ and $\overline{ADSC}$ are both asserted, only $\overline{ADSP}$ is recognized. $\overline{ASDP}$ is ignored when $\overline{CE}_1$ is deasserted HIGH.
$\overline{ADSC}$	Input-synchronous	**Address strobe from controller, sampled on the rising edge of CLK, active LOW**. When asserted LOW, addresses presented to the device are captured in the address registers. A1:A0 are also loaded into the burst counter. When $\overline{ADSP}$ and $\overline{ADSC}$ are both asserted, only $\overline{ADSP}$ is recognized.
ZZ	Input-asynchronous	**ZZ "sleep" input, active HIGH**. When asserted HIGH places the device in a non-time-critical "sleep" condition with data integrity preserved. For normal operation, this pin has to be LOW or left floating. ZZ pin has an internal pull-down.
DQs, DQPs	I/O-synchronous	**Bidirectional data I/O lines**. As inputs, they feed into an on-chip data register that is triggered by the rising edge of CLK. As outputs, they deliver the data contained in the memory location specified by the addresses presented during the previous clock rise of the read cycle. The direction of the pins is controlled by $\overline{OE}$. When $\overline{OE}$ is asserted LOW, the pins behave as outputs. When HIGH, DQs and DQP_X are placed in a tri-state condition.
V_{DD}	Power supply	**Power supply inputs to the core of the device**.
V_{SS}	Ground	**Ground for the core of the device**.
V_{SSQ}	I/O ground	**Ground for the I/O circuitry**.
V_{DDQ}	I/O power supply	**Power supply for the I/O circuitry**.
MODE	Input-static	**Selects burst order**. When tied to GND selects linear burst sequence. When tied to V_{DD} or left floating selects interleaved burst sequence. This is a strap pin and should remain static during device operation. Mode pin has an internal pull-up.
NC	–	**No Connects**. Not internally connected to the die.

Pin Definitions *(continued)*

Name	I/O	Description
NC/72M, NC/144M, NC/288M, NC/576M, NC/1G	–	**No Connects**. Not internally connected to the die. 72M, 144M, 288M, 576M and 1G are address expansion pins are not internally connected to the die.

Functional Overview

All synchronous inputs pass through input registers controlled by the rising edge of the clock. All data outputs pass through output registers controlled by the rising edge of the clock.

The CY7C1444AV33 supports secondary cache in systems utilizing either a linear or interleaved burst sequence. The interleaved burst order supports Pentium and i486™ processors. The linear burst sequence is suited for processors that utilize a linear burst sequence. The burst order is user selectable, and is determined by sampling the MODE input. Accesses can be initiated with either the processor address strobe ($\overline{ADSP}$) or the controller address strobe ($\overline{ADSC}$). Address advancement through the burst sequence is controlled by the ADV input. A two-bit on-chip wraparound burst counter captures the first address in a burst sequence and automatically increments the address for the rest of the burst access.

Byte write operations are qualified with the byte write enable ($\overline{BWE}$) and byte write select ($\overline{BW_X}$) inputs. A global write enable ($\overline{GW}$) overrides all byte write inputs and writes data to all four bytes. All writes are simplified with on-chip synchronous self-timed write circuitry.

Synchronous chip selects $\overline{CE_1}$, CE_2, $\overline{CE_3}$ and an asynchronous output enable ($\overline{OE}$) provide for easy bank selection and output tri-state control. $\overline{ADSP}$ is ignored if $\overline{CE_1}$ is HIGH.

Single Read Accesses

This access is initiated when the following conditions are satisfied at clock rise: (1) $\overline{ADSP}$ or $\overline{ADSC}$ is asserted LOW, (2) chip selects are all asserted active, and (3) the write signals ($\overline{GW}$, $\overline{BWE}$) are all deasserted HIGH. $\overline{ADSP}$ is ignored if $\overline{CE_1}$ is HIGH. The address presented to the address inputs is stored into the address advancement logic and the address register while being presented to the memory core. The corresponding data is allowed to propagate to the input of the output registers. At the rising edge of the next clock the data is allowed to propagate through the output register and onto the data bus within t_{CO} if $\overline{OE}$ is active LOW. The only exception occurs when the SRAM is emerging from a deselected state to a selected state, its outputs are always tri-stated during the first cycle of the access. After the first cycle of the access, the outputs are controlled by the $\overline{OE}$ signal. Consecutive single read cycles are supported.

The CY7C1444AV33 is a double-cycle deselect part. Once the SRAM is deselected at clock rise by the chip select and either $\overline{ADSP}$ or $\overline{ADSC}$ signals, its output will tri-state immediately after the next clock rise.

Single Write Accesses Initiated by $\overline{ADSP}$

This access is initiated when both of the following conditions are satisfied at clock rise: (1) $\overline{ADSP}$ is asserted LOW, and (2) chip select is asserted active. The address presented is loaded into the address register and the address advancement logic while being delivered to the memory core. The write signals ($\overline{GW}$, $\overline{BWE}$, and $\overline{BW_X}$) and ADV inputs are ignored during this first cycle.

$\overline{ADSP}$ triggered write accesses require two clock cycles to complete. If $\overline{GW}$ is asserted LOW on the second clock rise, the data presented to the DQ_X inputs is written into the corresponding address location in the memory core. If $\overline{GW}$ is HIGH, then the write operation is controlled by $\overline{BWE}$ and $\overline{BW_X}$ signals. The CY7C1444AV33 provides byte write capability that is described in the Write Cycle Description table. Asserting the byte write enable input ($\overline{BWE}$) with the selected byte write input will selectively write to only the desired bytes. Bytes not selected during a byte write operation will remain unaltered. A synchronous self-timed write mechanism has been provided to simplify the write operations.

Because the CY7C1444AV33 is a common I/O device, the output enable ($\overline{OE}$) must be deasserted HIGH before presenting data to the DQ inputs. Doing so will tri-state the output drivers. As a safety precaution, DQ are automatically tri-stated whenever a write cycle is detected, regardless of the state of $\overline{OE}$.

Single Write Accesses Initiated by $\overline{ADSC}$

$\overline{ADSC}$ write accesses are initiated when the following conditions are satisfied: (1) $\overline{ADSC}$ is asserted LOW, (2) $\overline{ADSP}$ is deasserted HIGH, (3) chip select is asserted active, and (4) the appropriate combination of the write inputs ($\overline{GW}$, $\overline{BWE}$, and $\overline{BW_X}$) are asserted active to conduct a write to the desired byte(s). $\overline{ADSC}$ triggered write accesses require a single clock cycle to complete. The address presented is loaded into the address register and the address advancement logic while being delivered to the memory core. The ADV input is ignored during this cycle. If a global write is conducted, the data presented to the DQ_X is written into the corresponding address location in the memory core. If a byte write is conducted, only the selected bytes are written. Bytes not selected during a byte write operation will remain unaltered. A synchronous self-timed write mechanism has been provided to simplify the write operations.

Because the CY7C1444AV33 is a common I/O device, the output enable ($\overline{OE}$) must be deasserted HIGH before presenting data to the DQ_X inputs. Doing so will tri-state the output drivers. As a safety precaution, DQ_X are automatically tri-stated whenever a write cycle is detected, regardless of the state of $\overline{OE}$.

Burst Sequences

The CY7C1444AV33 provides a two-bit wraparound counter, fed by $A_{[1:0]}$, that implements either an interleaved or linear burst sequence. The interleaved burst sequence is designed specifically to support Intel Pentium applications. The linear burst sequence is designed to support processors that follow a linear burst sequence. The burst sequence is user selectable

through the MODE input. Both read and write burst operations are supported.

Asserting $\overline{ADV}$ LOW at clock rise will automatically increment the burst counter to the next address in the burst sequence. Both read and write burst operations are supported.

Sleep Mode

The ZZ input pin is an asynchronous input. Asserting ZZ places the SRAM in a power conservation “sleep” mode. Two clock cycles are required to enter into or exit from this “sleep” mode. While in this mode, data integrity is guaranteed. Accesses pending when entering the “sleep” mode are not considered valid nor is the completion of the operation guaranteed. The device must be deselected prior to entering the “sleep” mode. $\overline{CE}$s, $\overline{ADSP}$, and $\overline{ADSC}$ must remain inactive for the duration of t_{ZZREC} after the ZZ input returns LOW.

Interleaved Burst Address Table

(MODE = Floating or V_{DD})

First Address A1:A0	Second Address A1:A0	Third Address A1:A0	Fourth Address A1:A0
00	01	10	11
01	00	11	10
10	11	00	01
11	10	01	00

Linear Burst Address Table

(MODE = GND)

First Address A1:A0	Second Address A1:A0	Third Address A1:A0	Fourth Address A1:A0
00	01	10	11
01	10	11	00
10	11	00	01
11	00	01	10

ZZ Mode Electrical Characteristics

Parameter	Description	Test Conditions	Min	Max	Unit
I_{DDZZ}	Sleep mode standby current	ZZ ≥ V_{DD} – 0.2 V	–	100	mA
t_{ZZS}	Device operation to ZZ	ZZ ≥ V_{DD} – 0.2 V	–	$2t_{CYC}$	ns
t_{ZZREC}	ZZ recovery time	ZZ ≤ 0.2 V	$2t_{CYC}$	–	ns
t_{ZZI}	ZZ active to sleep current	This parameter is sampled	–	$2t_{CYC}$	ns
t_{RZZI}	ZZ inactive to exit sleep current	This parameter is sampled	0	–	ns

Truth Table

The truth table for CY7C1444AV33 follows. [1, 2, 3, 4, 5, 6]

Operation	Add. Used	$\overline{CE_1}$	CE_2	$\overline{CE_3}$	ZZ	ADSP	ADSC	ADV	WRITE	OE	CLK	DQ
Deselect cycle, power-down	None	H	X	X	L	X	L	X	X	X	L–H	Tri-state
Deselect cycle, power-down	None	L	L	X	L	L	X	X	X	X	L–H	Tri-state
Deselect cycle, power-down	None	L	X	H	L	L	X	X	X	X	L–H	Tri-state
Deselect cycle, power-down	None	L	L	X	L	H	L	X	X	X	L–H	Tri-state
Deselect cycle, power-down	None	L	X	H	L	H	L	X	X	X	L–H	Tri-state
Sleep mode, power-down	None	X	X	X	H	X	X	X	X	X	X	Tri-state
Read cycle, begin burst	External	L	H	L	L	L	X	X	X	L	L–H	Q
Read cycle, begin burst	External	L	H	L	L	L	X	X	X	H	L–H	Tri-state
Write cycle, begin burst	External	L	H	L	L	H	L	X	L	X	L–H	D
Read cycle, begin burst	External	L	H	L	L	H	L	X	H	L	L–H	Q
Read cycle, begin burst	External	L	H	L	L	H	L	X	H	H	L–H	Tri-state
Read cycle, continue burst	Next	X	X	X	L	H	H	L	H	L	L–H	Q
Read cycle, continue burst	Next	X	X	X	L	H	H	L	H	H	L–H	Tri-state
Read cycle, continue burst	Next	H	X	X	L	X	H	L	H	L	L–H	Q
Read cycle, continue burst	Next	H	X	X	L	X	H	L	H	H	L–H	Tri-state
Write cycle, continue burst	Next	X	X	X	L	H	H	L	L	X	L–H	D
Write cycle, continue burst	Next	H	X	X	L	X	H	L	L	X	L–H	D
Read cycle, suspend burst	Current	X	X	X	L	H	H	H	H	L	L–H	Q
Read cycle, suspend burst	Current	X	X	X	L	H	H	H	H	H	L–H	Tri-state
Read cycle, suspend burst	Current	H	X	X	L	X	H	H	H	L	L–H	Q
Read cycle, suspend burst	Current	H	X	X	L	X	H	H	H	H	L–H	Tri-state
Write cycle, suspend burst	Current	X	X	X	L	H	H	H	L	X	L–H	D
Write cycle, suspend burst	Current	H	X	X	L	X	H	H	L	X	L–H	D

Notes

1. X = “Don't Care.” H = Logic HIGH, L = Logic LOW.
2. $\overline{WRITE}$ = L when any one or more byte write enable signals and $\overline{BWE}$ = L or $\overline{GW}$ = L. $\overline{WRITE}$ = H when all byte write enable signals, $\overline{BWE}$, $\overline{GW}$ = H.
3. The DQ pins are controlled by the current cycle and the $\overline{OE}$ signal. $\overline{OE}$ is asynchronous and is not sampled with the clock.
4. $\overline{CE_1}$, CE_2, and $\overline{CE_3}$ are available only in the TQFP package.
5. The SRAM always initiates a read cycle when $\overline{ADSP}$ is asserted, regardless of the state of $\overline{GW}$, $\overline{BWE}$, or $\overline{BW_X}$. Writes may occur only on subsequent clocks after the $\overline{ADSP}$ or with the assertion of $\overline{ADSC}$. As a result, $\overline{OE}$ must be driven HIGH prior to the start of the write cycle to allow the outputs to tri-state. $\overline{OE}$ is a don't care for the remainder of the write cycle.
6. $\overline{OE}$ is asynchronous and is not sampled with the clock rise. It is masked internally during write cycles. During a read cycle all data bits are tri-state when $\overline{OE}$ is inactive or when the device is deselected, and all data bits behave as output when $\overline{OE}$ is active (LOW).

Truth Table for Read/Write

The truth table for Read/Write for CY7C1444AV33 follows. [7, 8]

Function (CY7C1444AV33)	$\overline{GW}$	$\overline{BWE}$	$\overline{BW_D}$	$\overline{BW_C}$	$\overline{BW_B}$	$\overline{BW_A}$
Read	H	H	X	X	X	X
Read	H	L	H	H	H	H
Write byte A – (DQ_A and DQP_A)	H	L	H	H	H	L
Write byte B – (DQ_B and DQP_B)	H	L	H	H	L	H
Write bytes B, A	H	L	H	H	L	L
Write byte C – (DQ_C and DQP_C)	H	L	H	L	H	H
Write bytes C, A	H	L	H	L	H	L
Write bytes C, B	H	L	H	L	L	H
Write bytes C, B, A	H	L	H	L	L	L
Write byte D – (DQ_D and DQP_D)	H	L	L	H	H	H
Write bytes D, A	H	L	L	H	H	L
Write bytes D, B	H	L	L	H	L	H
Write bytes D, B, A	H	L	L	H	L	L
Write bytes D, C	H	L	L	L	H	H
Write bytes D, C, A	H	L	L	L	H	L
Write bytes D, C, B	H	L	L	L	L	H
Write all bytes	H	L	L	L	L	L
Write all bytes	L	X	X	X	X	X

Notes
7. The DQ pins are controlled by the current cycle and the $\overline{OE}$ signal. $\overline{OE}$ is asynchronous and is not sampled with the clock.
8. Table only lists a partial listing of the byte write combinations. Any Combination of $\overline{BW}_X$ is valid Appropriate write will be done based on which byte write is active.

Maximum Ratings

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Storage temperature ..... –65 °C to +150 °C

Ambient temperature with power applied ..... –55 °C to +125 °C

Supply voltage on V_{DD} relative to GND .....–0.5 V to +4.6 V

Supply voltage on V_{DDQ} relative to GND ..... –0.5 V to +V_{DD}

DC voltage applied to outputs in tri-state .....–0.5 V to V_{DDQ} + 0.5 V

DC input voltage ..... –0.5 V to V_{DD} + 0.5 V

Current into outputs (LOW) ..... 20 mA

Static discharge voltage (per MIL-STD-883, method 3015) ..... > 2001 V

Latch-up current ..... > 200 mA

Operating Range

Range	Ambient Temperature	V_{DD}	V_{DDQ}
Commercial	0 °C to +70 °C	3.3 V – 5% / + 10%	2.5 V – 5% to V_{DD}
Industrial	–40 °C to +85 °C		

Electrical Characteristics

Over the Operating Range

Parameter [9, 10]	Description	Test Conditions		Min	Max	Unit
V_{DD}	Power supply voltage			3.135	3.6	V
V_{DDQ}	I/O supply voltage	for 3.3 V I/O		3.135	V_{DD}	V
		for 2.5 V I/O		2.375	2.625	V
V_{OH}	Output HIGH voltage	for 3.3 V I/O, I_{OH} = –4.0 mA		2.4	–	V
		for 2.5 V I/O, I_{OH} = –1.0 mA		2.0	–	V
V_{OL}	Output LOW voltage	for 3.3 V I/O, I_{OL} = 8.0 mA		–	0.4	V
		for 2.5 V I/O, I_{OL} = 1.0 mA		–	0.4	V
V_{IH}	Input HIGH voltage [9]	for 3.3 V I/O		2.0	V_{DD} + 0.3	V
		for 2.5 V I/O		1.7	V_{DD} + 0.3	V
V_{IL}	Input LOW voltage [9]	for 3.3 V I/O		–0.3	0.8	V
		for 2.5 V I/O		–0.3	0.7	V
I_X	Input leakage current except ZZ and MODE	GND ≤ V_I ≤ V_{DDQ}		–5	5	µA
	Input current of MODE	Input = V_{SS}		–30	–	µA
		Input = V_{DD}		–	5	µA
	Input current of ZZ	Input = V_{SS}		–5	–	µA
		Input = V_{DD}		–	30	µA
I_{OZ}	Output leakage current	GND ≤ V_I ≤ V_{DDQ}, output disabled		–5	5	µA
I_{DD}	V_{DD} operating supply current	V_{DD} = Max, I_{OUT} = 0 mA, f = f_{MAX} = 1/t_{CYC}	4-ns cycle, 250 MHz	-	475	mA
			6-ns cycle, 167 MHz	–	375	mA

Notes

9. Overshoot: $V_{IH(AC)}$ < V_{DD} + 1.5 V (Pulse width less than t_{CYC}/2), undershoot: $V_{IL(AC)}$ > –2 V (Pulse width less than t_{CYC}/2).
10. $T_{Power-up}$: Assumes a linear ramp from 0 V to $V_{DD(min)}$ within 200 ms. During this time V_{IH} < V_{DD} and V_{DDQ} ≤ V_{DD}.

Electrical Characteristics *(continued)*

Over the Operating Range

Parameter [9, 10]	Description	Test Conditions		Min	Max	Unit
I_{SB1}	Automatic CE power-down current – TTL inputs	V_{DD} = Max, device deselected, $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL}$, f = f_{MAX} = $1/t_{CYC}$	All speeds	–	225	mA
I_{SB2}	Automatic CE power-down current – CMOS inputs	V_{DD} = Max, device deselected, $V_{IN} \leq 0.3$ V or $V_{IN} \geq V_{DDQ} - 0.3$ V, f = 0	All speeds	–	120	mA
I_{SB3}	Automatic CE power-down current – CMOS inputs	V_{DD} = Max, device deselected, or $V_{IN} \leq 0.3$ V or $V_{IN} \geq V_{DDQ} - 0.3$ V, f = f_{MAX} = $1/t_{CYC}$	All speeds	–	200	mA
I_{SB4}	Automatic CE power-down current – TTL inputs	V_{DD} = Max, device deselected, $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL}$, f = 0	All speeds	–	135	mA

Capacitance

Parameter [11]	Description	Test Conditions	100-pin TQFP Max	Unit
C_{IN}	Input capacitance	T_A = 25 °C, f = 1 MHz, V_{DD} = 3.3 V, V_{DDQ} = 2.5 V	6.5	pF
C_{CLK}	Clock input capacitance		3	pF
$C_{I/O}$	Input/output capacitance		5.5	pF

Thermal Resistance

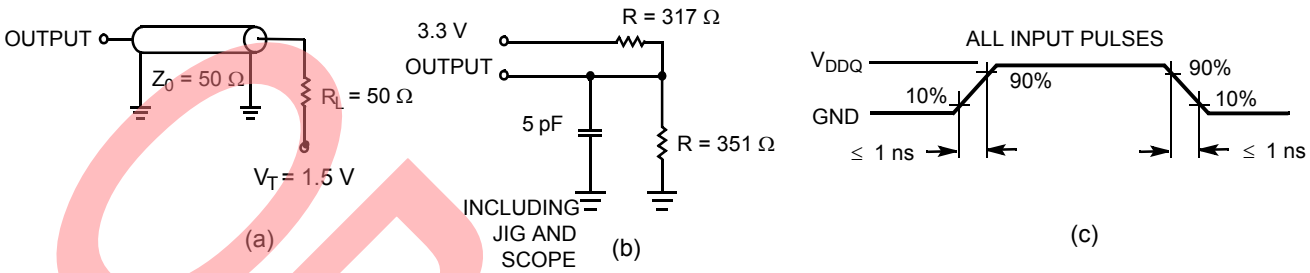
Parameter [11]	Description	Test Conditions	100-pin TQFP Package	Unit
Θ_{JA}	Thermal resistance (junction to ambient)	Test conditions follow standard test methods and procedures for measuring thermal impedance, per EIA/JESD51.	25.21	°C/W
Θ_{JC}	Thermal resistance (junction to case)		2.28	°C/W

Note
11. Tested initially and after any design or process change that may affect these parameters.

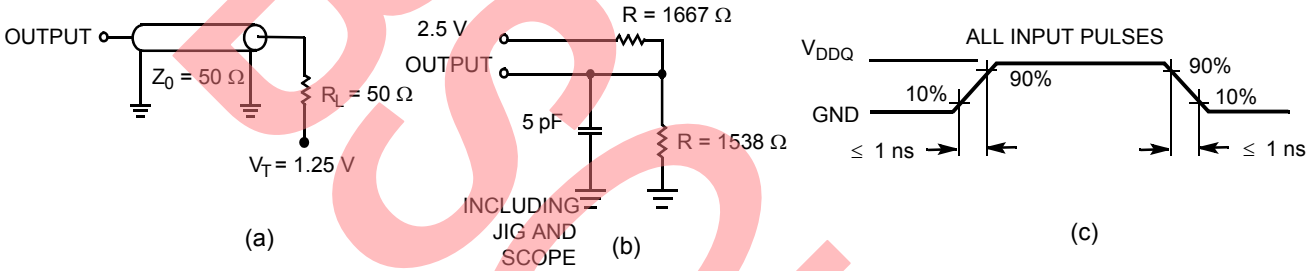
AC Test Loads and Waveforms

Figure 2. AC Test Loads and Waveforms

3.3 V I/O Test Load



2.5 V I/O Test Load



Switching Characteristics

Over the Operating Range

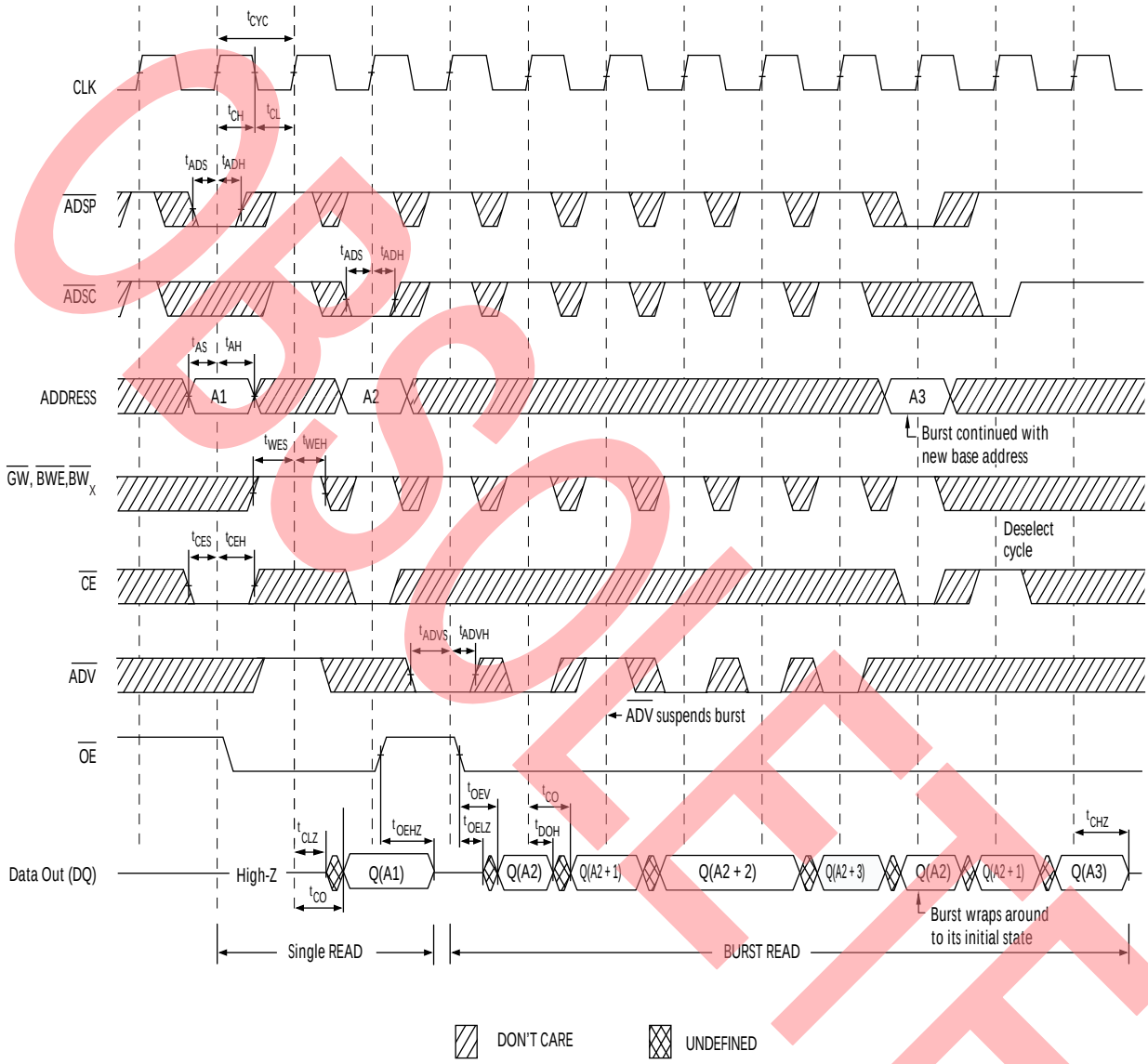
Parameter [12, 13]	Description	-250		-167		Unit
		Min	Max	Min	Max	
t_{POWER}	V_{DD}(typical) to the first access [14]	1	–	1	–	ms
Clock						
t_{CYC}	Clock cycle time	4	–	6	–	ns
t_{CH}	Clock HIGH	1.5	–	2.4	–	ns
t_{CL}	Clock LOW	1.5	–	2.4	–	ns
Output Times						
t_{CO}	Data output valid after CLK rise	–	3.4	–	3.4	ns
t_{DOH}	Data output hold after CLK rise	1.0	–	1.5	–	ns
t_{CLZ}	Clock to low Z [15, 16, 17]	1.0	–	1.5	–	ns
t_{CHZ}	Clock to high Z [15, 16, 17]	–	3.4	–	3.4	ns
t_{OEV}	$\overline{OE}$ LOW to output valid	–	3.4	–	3.4	ns
t_{OELZ}	$\overline{OE}$ LOW to output low Z [15, 16, 17]	0	–	0	–	ns
t_{OEHZ}	$\overline{OE}$ HIGH to output high Z [15, 16, 17]	–	3.4	–	3.4	ns
Set-up Times						
t_{AS}	Address set-up before CLK rise	1.2	–	1.5	–	ns
t_{ADS}	$\overline{ADSC}$, $\overline{ADSP}$ set-up before CLK rise	1.2	–	1.5	–	ns
t_{ADVS}	$\overline{ADV}$ set-up before CLK rise	1.2	–	1.5	–	ns
t_{WES}	$\overline{GW}$, $\overline{BWE}$, $\overline{BW_X}$ set-up before CLK rise	1.2	–	1.5	–	ns
t_{DS}	Data input set-up before CLK rise	1.2	–	1.5	–	ns
t_{CES}	Chip enable set-up before CLK rise	1.2	–	1.5	–	ns
Hold Times						
t_{AH}	Address hold after CLK rise	0.3	–	0.5	–	ns
t_{ADH}	$\overline{ADSP}$, $\overline{ADSC}$ hold after CLK rise	0.3	–	0.5	–	ns
t_{ADVH}	$\overline{ADV}$ hold after CLK rise	0.3	–	0.5	–	ns
t_{WEH}	$\overline{GW}$, $\overline{BWE}$, $\overline{BW_X}$ hold after CLK rise	0.3	–	0.5	–	ns
t_{DH}	Data input hold after CLK rise	0.3	–	0.5	–	ns
t_{CEH}	Chip enable hold after CLK rise	0.3	–	0.5	–	ns

Notes

12. Timing reference level is 1.5 V when V_{DDQ} = 3.3 V and is 1.25 V when V_{DDQ} = 2.5 V.
13. Test conditions shown in (a) of Figure 2 on page 12 unless otherwise noted.
14. This part has a voltage regulator internally; t_{POWER} is the time that the power needs to be supplied above $V_{DD(minimum)}$ initially before a read or write operation can be initiated.
15. t_{CHZ}, t_{CLZ},t_{OELZ}, and t_{OEHZ} are specified with AC test conditions shown in part (b) of Figure 2 on page 12. Transition is measured ± 200 mV from steady-state voltage.
16. At any given voltage and temperature, t_{OEHZ} is less than t_{OELZ} and t_{CHZ} is less than t_{CLZ} to eliminate bus contention between SRAMs when sharing the same data bus. These specifications do not imply a bus contention condition, but reflect parameters guaranteed over worst case user conditions. Device is designed to achieve high Z prior to low Z under the same system conditions.
17. This parameter is sampled and not 100% tested.

Switching Waveforms

Figure 3. Read Cycle Timing [18]



Note
18. On this diagram, when $\overline{CE}$ is LOW: $\overline{CE}_1$ is LOW, CE_2 is HIGH and $\overline{CE}_3$ is LOW. When $\overline{CE}$ is HIGH: $\overline{CE}_1$ is HIGH or CE_2 is LOW or $\overline{CE}_3$ is HIGH.

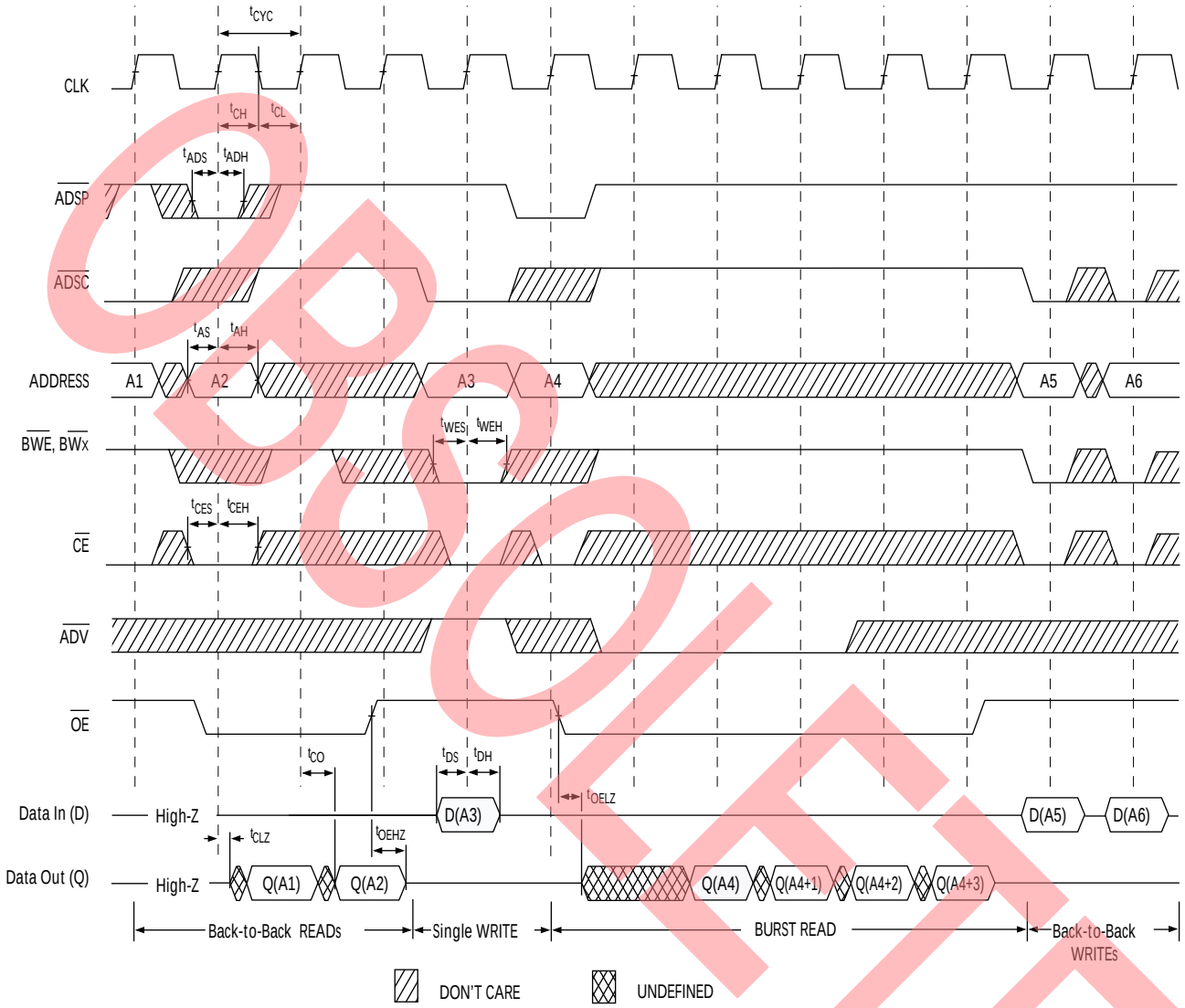
Switching Waveforms *(continued)*

Figure 4. Write Cycle Timing [19, 20]

Notes
19. On this diagram, when $\overline{CE}$ is LOW: $\overline{CE}_1$ is LOW, CE_2 is HIGH and $\overline{CE}_3$ is LOW. When $\overline{CE}$ is HIGH: $\overline{CE}_1$ is HIGH or CE_2 is LOW or $\overline{CE}_3$ is HIGH.
20. Full width write can be initiated by either $\overline{GW}$ LOW; or by $\overline{GW}$ HIGH, $\overline{BWE}$ LOW and $\overline{BW}_X$ LOW.

Switching Waveforms *(continued)*

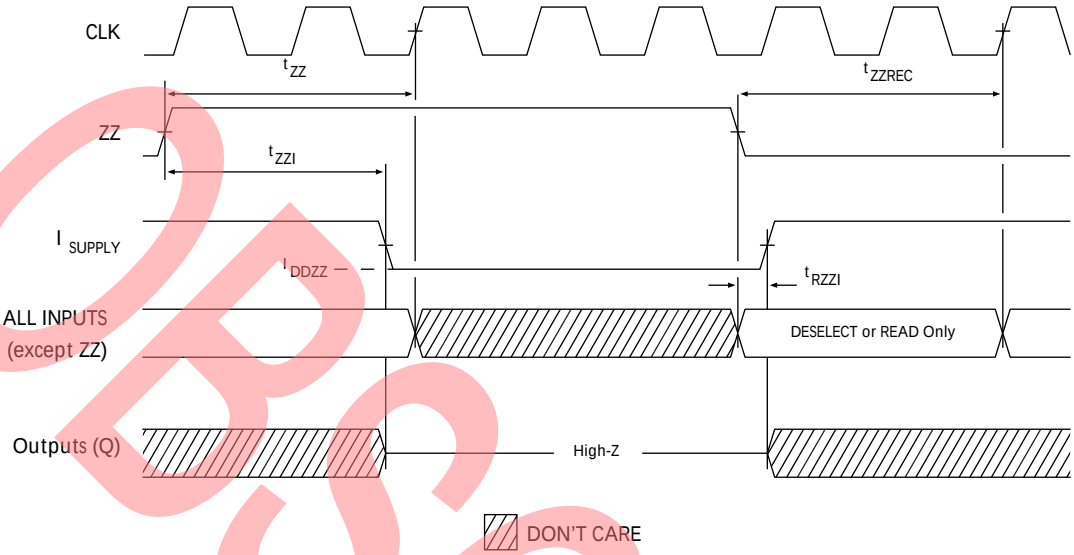
Figure 5. Read/Write Cycle Timing [21, 22, 23]



Notes
21. On this diagram, when $\overline{CE}$ is LOW: $\overline{CE}_1$ is LOW, CE_2 is HIGH and $\overline{CE}_3$ is LOW. When $\overline{CE}$ is HIGH: $\overline{CE}_1$ is HIGH or CE_2 is LOW or $\overline{CE}_3$ is HIGH.
22. The data bus (Q) remains in high Z following a Write cycle, unless a new read access is initiated by $\overline{ADSP}$ or $\overline{ADSC}$.
23. $\overline{GW}$ is HIGH.

Switching Waveforms *(continued)*

Figure 6. ZZ Mode Timing [24, 25]



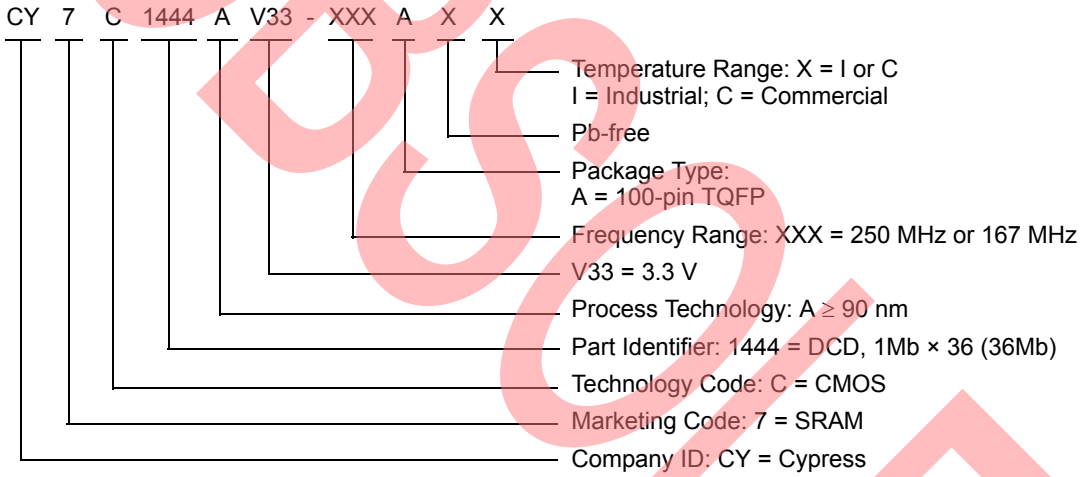
Notes
24. Device must be deselected when entering ZZ mode. See Cycle Descriptions table for all possible signal conditions to deselect the device.
25. DQs are in high Z when exiting ZZ sleep mode.

Ordering Information

Cypress offers other versions of this type of product in many different configurations and features. The below table contains only the list of parts that are currently available. For a complete listing of all options, visit the Cypress website at www.cypress.com and refer to the product summary page at http://www.cypress.com/products or contact your local sales representative. Cypress maintains a worldwide network of offices, solution centers, manufacturer's representatives and distributors. To find the office closest to you, visit us at http://www.cypress.com/go/datasheet/offices.

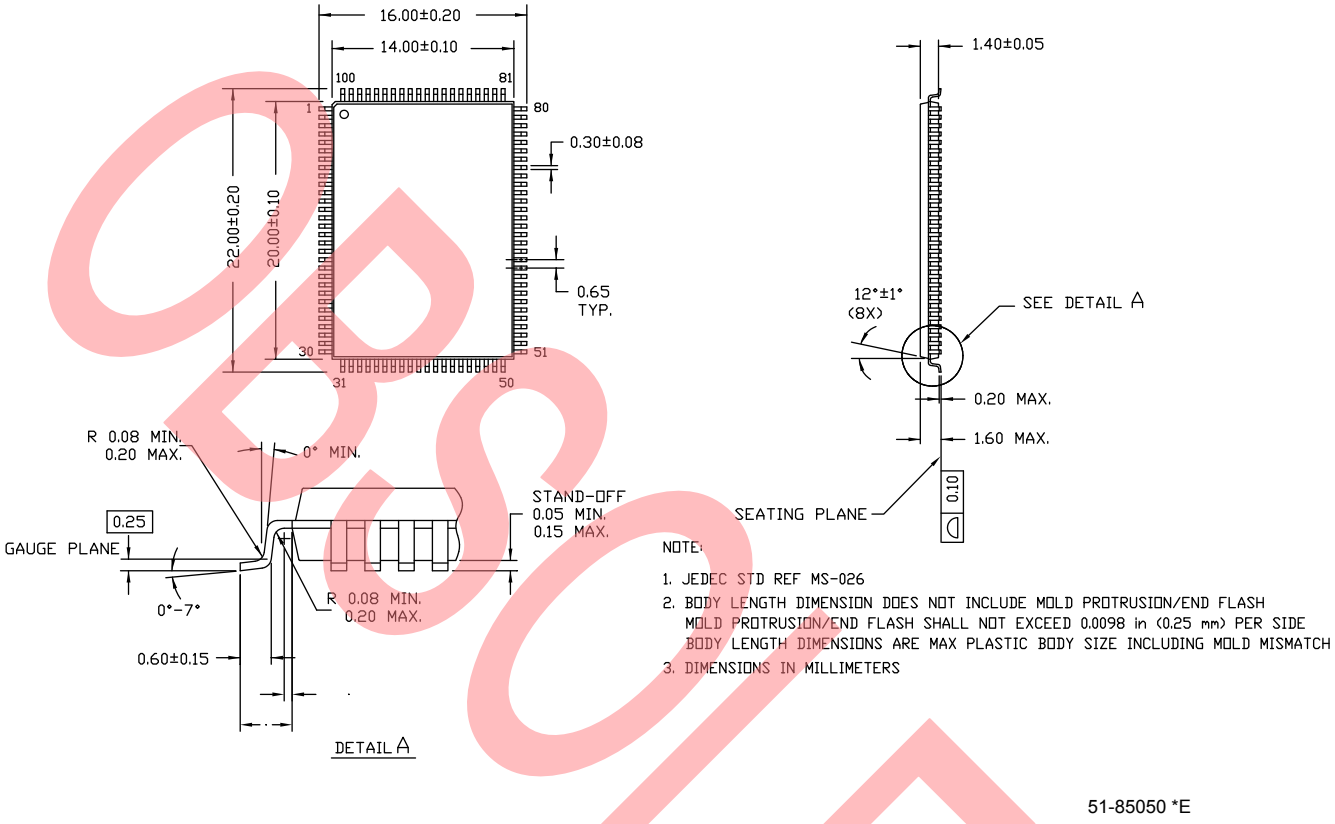
Speed (MHz)	Ordering Code	Package Diagram	Part and Package Type	Operating Range
250	CY7C1444AV33-250AXI	51-85050	100-pin TQFP (14 × 20 × 1.4 mm) Pb-free	Industrial
167	CY7C1444AV33-167AXC	51-85050	100-pin TQFP (14 × 20 × 1.4 mm) Pb-free	Commercial

Ordering Code Definitions



Package Diagram

Figure 7. 100-pin TQFP (14 × 20 × 1.4 mm) A100RA Package Outline, 51-85050



Acronyms

Acronym	Description
$\overline{CE}$	chip enable
CMOS	complementary metal oxide semiconductor
EIA	electronic industries alliance
I/O	input/output
JEDEC	joint electron devices engineering council
LSB	least significant bit
MSB	most significant bit
$\overline{OE}$	output enable
SRAM	static random access memory
TQFP	thin quad flat pack
TTL	transistor-transistor logic

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
MHz	megahertz
µA	microampere
mA	milliampere
mm	millimeter
ms	millisecond
mV	millivolt
nm	nanometer
ns	nanosecond
Ω	ohm
%	percent
pF	picofarad
V	volt
W	watt

Document History Page

Document Title: CY7C1444AV33, 36-Mbit (1M × 36) Pipelined DCD Sync SRAM Document Number: 38-05352				
Rev.	**ECN No.**	**Submission Date**	**Orig. of Change**	**Description of Change**
**	124419	03/04/03	CGM	New data sheet.
*A	254910	See ECN	SYT	Updated Logic Block Diagram – CY7C1444AV33. Updated Logic Block Diagram – CY7C1445AV33. Updated Identification Register Definitions (Added Note “Bit #24 is “1” in the ID Register Definitions for both 2.5 V and 3.3 V versions of this device.” and referred the same in Device Depth (28:24)). Added Boundary Scan Order related information. Updated Electrical Characteristics (Updated values of I_{DD}, I_X and I_{SB} parameters). Updated Switching Characteristics (Added t_{POWER} parameter and its details). Updated Switching Waveforms. Updated Package Diagram (Removed 119-ball PBGA package, changed 165-ball FBGA package from BB165C (15 × 17 × 1.20 mm) to BB165 (15 × 17 × 1.40 mm)).
*B	303533	See ECN	SYT	Updated Electrical Characteristics (Changed Test Condition from V_{DD} = Min. to V_{DD} = Max for V_{OL} parameter, changed maximum value of I_{DD} from 450 mA, 400 mA, and 350 mA to 475 mA, 425 mA, and 375 mA for 250 MHz, 200 MHz, and 167 MHz frequencies respectively, changed maximum value of I_{SB1} parameter from 190 mA, 180 mA, and 170 mA to 225 mA for 250 MHz, 200 MHz, and 167 MHz frequencies respectively, changed maximum value of I_{SB2} parameter from 80 mA to 100 mA for all frequencies, changed maximum value of I_{SB3} from 180 mA, 170 mA, and 160 mA to 200 mA for 250 MHz, 200 MHz, and 167 MHz respectively, changed maximum value of I_{SB4} parameter from 100 mA to 110 mA for all frequencies). Updated Capacitance (Changed value of C_{IN}, C_{CLK} and $C_{I/O}$ to 6.5 pF, 3 pF, and 5.5 pF from 5 pF, 5 pF, and 7 pF for 100-pin TQFP Package). Updated Thermal Resistance (Replaced values of Θ_{JA} and Θ_{JC} parameters from TBD to respective Thermal Values for all Packages). Updated Switching Characteristics (Changed maximum value of t_{CO} parameter from 3.0 ns to 3.2 ns for 200 MHz frequency, changed minimum value of t_{DOH} parameter from 1.3 ns to 1.5 ns for 200 MHz frequency). Updated Ordering Information (Added lead-free information for 100-pin TQFP and 165-ball FBGA packages).
*C	331778	See ECN	SYT	Updated Pin Configurations (Modified Address Expansion balls in the pinouts for 165-ball FBGA Package as per JEDEC standards). Updated Pin Definitions. Updated Operating Range (Added Industrial Temperature Range). Updated Electrical Characteristics (Updated Test Conditions of V_{OL}, V_{OH} parameters, changed maximum value of I_{SB2} and I_{SB4} parameters from 100 mA and 110 mA to 120 mA and 135 mA respectively). Updated Capacitance (Changed value of C_{IN}, C_{CLK} and $C_{I/O}$ to 7 pF, 7 pF, and 6 pF from 5 pF, 5 pF, and 7 pF for 165-ball FBGA Package). Updated Ordering Information (By shading and Unshading MPNs as per availability).

Document History Page *(continued)*

Document Title: CY7C1444AV33, 36-Mbit (1M × 36) Pipelined DCD Sync SRAM Document Number: 38-05352				
Rev.	**ECN No.**	**Submission Date**	**Orig. of Change**	**Description of Change**
*D	417509	See ECN	RXU	Changed status from Preliminary to Final. Changed address of Cypress Semiconductor Corporation from “3901 North First Street” to “198 Champion Court”. Updated Electrical Characteristics (Updated Note 10 (Modified test condition from $V_{IH} \leq V_{DD}$ to $V_{IH} < V_{DD}$), changed “Input Load Current except ZZ and MODE” to “Input Leakage Current except ZZ and MODE”, changed minimum value of I_X corresponding to Input current of MODE (Input = V_{SS}) from –5 µA to –30 µA, changed maximum value of I_X corresponding to Input current of MODE (Input = V_{DD}) from 30 µA to 5 µA respectively, changed minimum value of I_X corresponding to Input current of ZZ (Input = V_{SS}) from –30 µA to –5 µA, changed maximum value of I_X corresponding to Input current of ZZ (Input = V_{DD}) from 5 µA to 30 µA). Updated Ordering Information (Replaced Package Name column with Package Diagram in the Ordering Information table). Updated Package Diagram (spec 51-85050 (changed revision from *A to *B)).
*E	473229	See ECN	VKN	Updated TAP AC Switching Characteristics (Changed minimum value of t_{TH}, t_{TL} parameters from 25 ns to 20 ns, changed maximum value of t_{TDOV} parameter from 5 ns to 10 ns). Updated Maximum Ratings (Added the Maximum Rating for Supply Voltage on V_{DDQ} Relative to GND). Updated Ordering Information (Updated part numbers).
*F	2898663	03/24/2010	NJY	Updated Ordering Information (Removed inactive parts). Updated Package Diagram.
*G	3042209	09/29/2010	NJY	Added Ordering Code Definitions. Added Acronyms and Units of Measure. Minor edits. Updated to new template.
*H	3263545	05/23/2011	NJY	Updated Package Diagram.
*I	3363203	09/05/2011	PRIT	Updated to new template.

Document History Page *(continued)*

Document Title: CY7C1444AV33, 36-Mbit (1M × 36) Pipelined DCD Sync SRAM Document Number: 38-05352				
Rev.	**ECN No.**	**Submission Date**	**Orig. of Change**	**Description of Change**
*J	3616631	05/14/2012	PRIT	Updated Features (Removed 250 MHz, 200 MHz frequencies related information, removed CY7C1445AV33 related information, removed 165-ball FBGA package related information). Updated Functional Description (Removed CY7C1445AV33 related information, removed the Note “For best-practices recommendations, please refer to the Cypress application note *System Design Guidelines* on www.cypress.com.” and its reference). Updated Selection Guide (Removed 250 MHz, 200 MHz frequencies related information). Removed Logic Block Diagram – CY7C1445AV33. Updated Pin Configurations (Removed CY7C1445AV33 related information, removed 165-ball FBGA package related information). Updated Pin Definitions (Removed JTAG related information). Updated Functional Overview (Removed CY7C1445AV33 related information). Updated Truth Table (Removed CY7C1445AV33 related information). Removed Truth Table for Read/Write (Corresponding to CY7C1445AV33). Removed IEEE 1149.1 Serial Boundary Scan (JTAG). Removed TAP Controller State Diagram. Removed TAP Controller Block Diagram. Removed TAP Timing. Removed TAP AC Switching Characteristics. Removed 3.3 V TAP AC Test Conditions. Removed 3.3 V TAP AC Output Load Equivalent. Removed 2.5 V TAP AC Test Conditions. Removed 2.5 V TAP AC Output Load Equivalent. Removed TAP DC Electrical Characteristics and Operating Conditions. Removed Identification Register Definitions. Removed Scan Register Sizes. Removed Instruction Codes. Removed Boundary Scan Order. Updated Operating Range (Removed Industrial Temperature Range). Updated Electrical Characteristics (Removed 250 MHz, 200 MHz frequencies related information). Updated Capacitance (Removed 165-ball FBGA package related information). Updated Thermal Resistance (Removed 165-ball FBGA package related information). Updated Switching Characteristics (Removed 250 MHz, 200 MHz frequencies related information).
*K	3753416	09/24/2012	PRIT	No technical updates. Completing Sunset Review.
*L	3800874	11/02/2012	PRIT	Updated Features (Included 250 MHz frequency related information). Updated Selection Guide (Included 250 MHz frequency related information). Updated Operating Range (Included Industrial Temperature Range). Updated Electrical Characteristics (Included 250 MHz frequency related information). Updated Switching Characteristics (Included 250 MHz frequency related information). Updated Ordering Information (Updated part numbers).
*M	4571917	11/18/2014	PRIT	Updated Functional Description: Added “For a complete list of related documentation, click here.” at the end. Updated Package Diagram (spec 51-85050 to most current revision).
*N	5506925	11/02/2016	PRIT	Obsolete document. Completing Sunset Review.

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